

# Model : MBA27005 Series



## BGA Heat Sink Specification

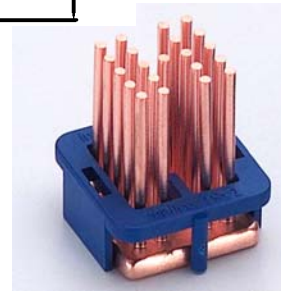
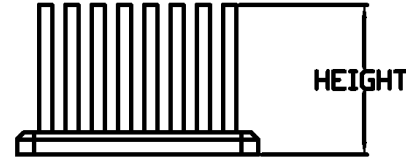
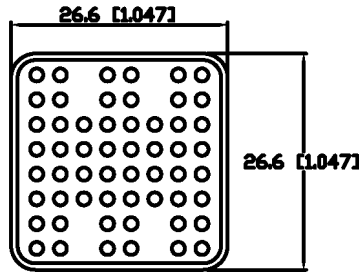
For 27x27 Chip set

- 1. Material : CU1100
- 2. Dimension :  
Foot print : 27x27mm  
Height : 12,15,18,21,23,28,33 mm  
Base (thickness) : 2.6mm

3. Finish: Antioxidant Treatment

- 4. Chip set package thickness and clip color  
3.3+/-0.25mm - Yellow clip  
1.7+/-0.25mm - Blue clip  
0.8+/-0.25mm - Orange clip

- 5. Accessory :  
Clip : Plastic (UL94-V0)  
Thermal pad : T710 or others



## Performance

Heat Source (LxW)	15x15
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